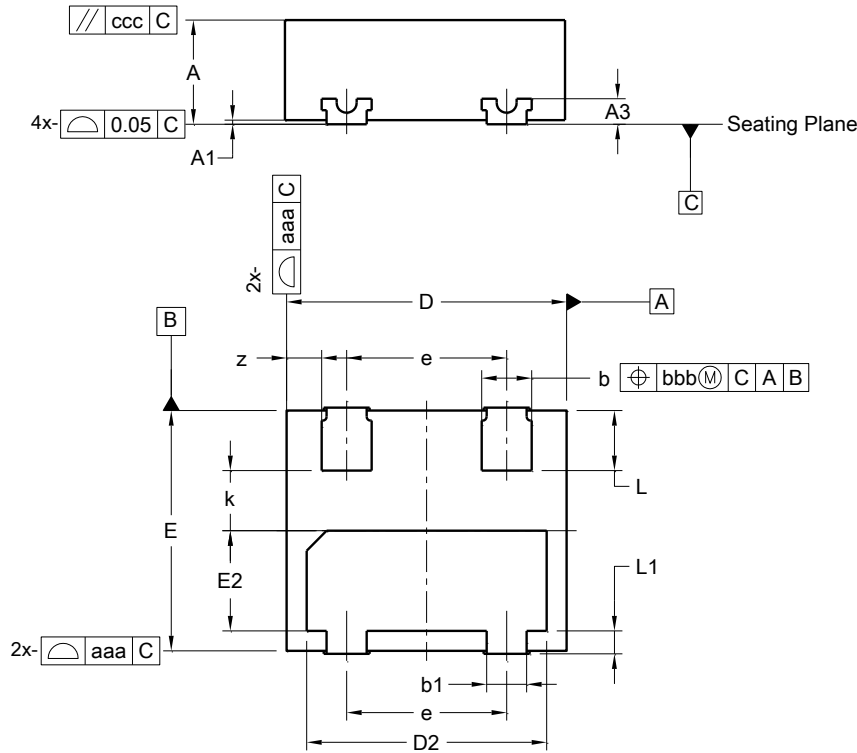


**Package Outline Dimensions**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**U-DFN1412-3/SWP (Type A)**



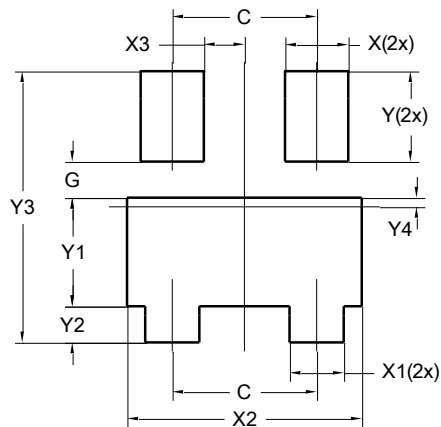
U-DFN1412-3/SWP (Type A)			
Dim	Min	Max	Typ
A	0.47	0.57	0.52
A1	0.00	0.05	0.03
A3	-	-	0.127
b	0.22	0.30	0.25
b1	0.15	0.25	0.20
D	1.35	1.45	1.40
D2	1.17	1.25	1.20
e	0.80 BSC		
E	1.15	1.25	1.20
E2	0.47	0.55	0.50
k	-	-	0.30
L	0.25	0.35	0.30
L1	0.065	0.165	0.115
z	-	-	0.175
aaa	0.25		
bbb	0.10		
ccc	0.10		
All Dimensions in mm			

Note: Side wall tin plated package for wettable flanks in AOI.

**Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**U-DFN1412-3/SWP (Type A)**



Dimensions	Value (in mm)
C	0.800
G	0.200
X	0.350
X1	0.300
X2	1.300
X3	0.225
Y	0.500
Y1	0.600
Y2	0.200
Y3	1.500

**ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS**

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.